

**Description**

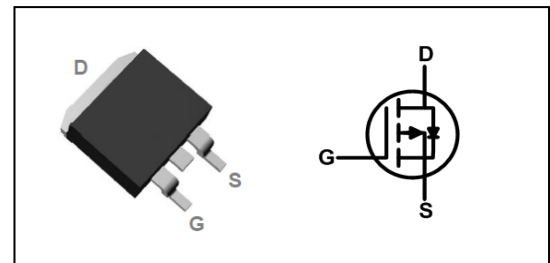
The HSH4119 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The HSH4119 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

**Product Summary**

|                         |      |    |
|-------------------------|------|----|
| V <sub>DS</sub>         | -40  | V  |
| R <sub>DS(ON),typ</sub> | 3.9  | mΩ |
| I <sub>D</sub>          | -150 | A  |

**TO-263 Pin Configuration**

**Absolute Maximum Ratings**

| Symbol                                | Parameter   | Rating     | Units |
|---------------------------------------|---|------------|-------|
| V <sub>DS</sub>                       | Drain-Source Voltage  | -40        | V     |
| V <sub>GS</sub>                       | Gate-Source Voltage   | ±20        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25°C  | Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1,6</sup> | -150       | A     |
| I <sub>D</sub> @T <sub>C</sub> =100°C | Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1,6</sup> | -103       | A     |
| I <sub>DM</sub>                       | Pulsed Drain Current <sup>2</sup>                               | -580       | A     |
| EAS                                   | Single Pulse Avalanche Energy <sup>3</sup>                      | 1250       | mJ    |
| I <sub>AS</sub>                       | Avalanche Current   | -70        | A     |
| P <sub>D</sub> @T <sub>C</sub> =25°C  | Total Power Dissipation <sup>4</sup>                            | 200        | W     |
| T <sub>STG</sub>                      | Storage Temperature Range                                       | -55 to 150 | °C    |
| T <sub>J</sub>                        | Operating Junction Temperature Range                            | -55 to 150 | °C    |

**Thermal Data**

| Symbol           | Parameter   | Typ. | Max. | Unit |
|------------------|---|------|------|------|
| R <sub>θJA</sub> | Thermal Resistance Junction-ambient <sup>1</sup> (Steady State) | ---  | 62   | °C/W |
| R <sub>θJC</sub> | Thermal Resistance Junction-case <sup>1</sup>                   | ---  | 0.95 | °C/W |

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**

| Symbol       | Parameter                                      | Conditions  | Min. | Typ.  | Max.      | Unit      |
|--------------|--|---|------|-------|-----------|-----------|
| $BV_{DSS}$   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V, I_D=-250\mu A$                        | -40  | ---   | ---       | V         |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=-10V, I_D=-30A$                           | ---  | 3.9   | 4.5       | $m\Omega$ |
|              |  | $V_{GS}=-4.5V, I_D=-20A$                          | ---  | 4.9   | 5.6       | $m\Omega$ |
| $V_{GS(th)}$ | Gate Threshold Voltage                         | $V_{GS}=V_{DS}, I_D=-250\mu A$                    | -1.0 | ---   | -2.5      | V         |
| $I_{DSS}$    | Drain-Source Leakage Current                   | $V_{DS}=-40V, V_{GS}=0V, T_J=25^\circ C$          | ---  | ---   | -1        | $\mu A$   |
|              |  | $V_{DS}=-40V, V_{GS}=0V, T_J=125^\circ C$         | ---  | ---   | -100      | $\mu A$   |
| $I_{GSS}$    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V, V_{DS}=0V$                       | ---  | ---   | $\pm 100$ | nA        |
| $R_g$        | Gate resistance                                | $V_{DS}=0V, V_{GS}=0V, f=1MHz$                    |      | 1.7   |           | $\Omega$  |
| $Q_g$        | Total Gate Charge (-10V)                       | $V_{DS}=-20V, V_{GS}=-10V, I_D=-20A$              | ---  | 190   | ---       | nC        |
| $Q_{gs}$     | Gate-Source Charge                             |   | ---  | 24    | ---       |           |
| $Q_{gd}$     | Gate-Drain Charge                              |   | ---  | 38    | ---       |           |
| $T_{d(on)}$  | Turn-On Delay Time                             | $V_{DD}=-20V, V_{GS}=-10V, R_G=3\Omega, I_D=-10A$ | ---  | 18    | ---       | ns        |
| $T_r$        | Rise Time                                      |   | ---  | 3.6   | ---       |           |
| $T_{d(off)}$ | Turn-Off Delay Time                            |   | ---  | 21    | ---       |           |
| $T_f$        | Fall Time                                      |   | ---  | 39    | ---       |           |
| $C_{iss}$    | Input Capacitance                              | $V_{DS}=-20V, V_{GS}=0V, f=1MHz$                  | ---  | 10700 | ---       | pF        |
| $C_{oss}$    | Output Capacitance                             |   | ---  | 780   | ---       |           |
| $C_{rss}$    | Reverse Transfer Capacitance                   |   | ---  | 660   | ---       |           |

**Diode Characteristics**

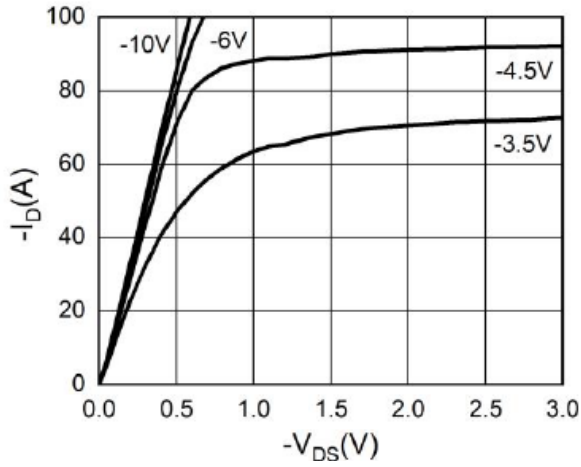
| Symbol   | Parameter                                | Conditions                            | Min. | Typ. | Max. | Unit |
|----------|--|---------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,5</sup> | $V_G=V_D=0V$ , Force Current          | ---  | ---  | -150 | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V, I_S=-20A, T_J=25^\circ C$ | ---  | ---  | -1.2 | V    |
| $t_{rr}$ | Reverse Recovery Time                    | $I_F=-20A, di/dt=100A/\mu s,$         | ---  | 52   | ---  | nS   |
| $Q_{rr}$ | Reverse Recovery Charge                  | $T_J=25^\circ C$                      | ---  | 128  | ---  | nC   |

Note :

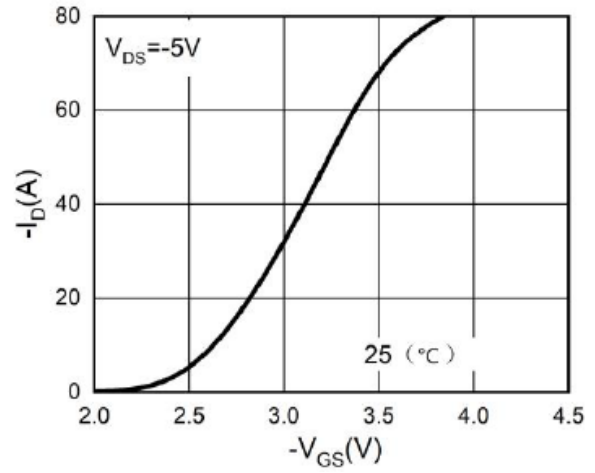
- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=-40V, V_{GS}=-10V, L=0.5mH, I_{AS}=-70A$
- 4.The power dissipation is limited by 150 $^\circ C$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation
- 6.The maximum current rating is package limited.



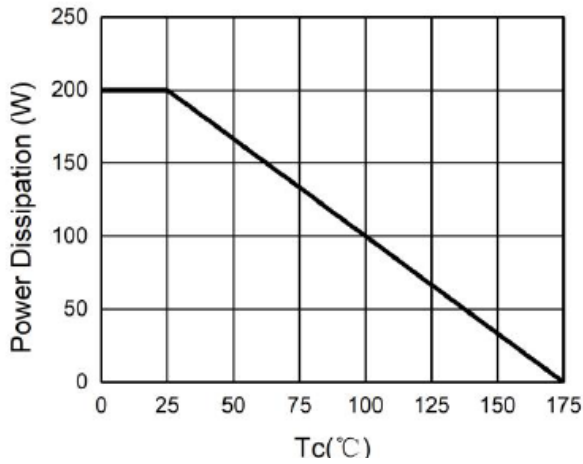
**Typical Characteristics**



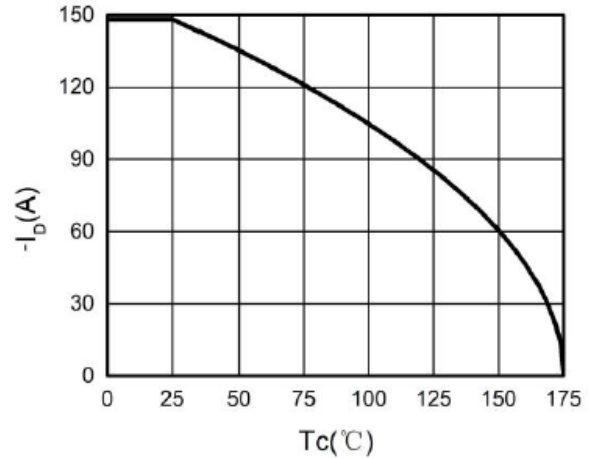
**Fig.1 Output Characteristics**



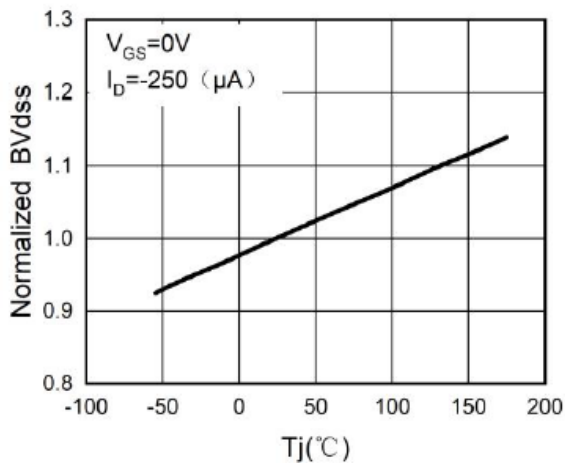
**Fig.2 Transfer Characteristics**



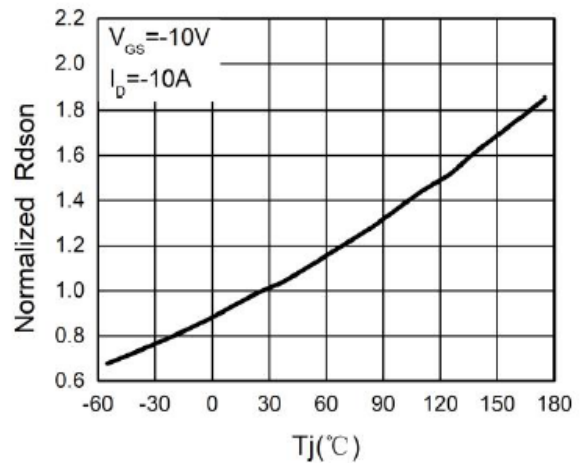
**Fig.3 Power Dissipation**



**Fig.4 Drain Current**



**Fig.5  $BV_{dss}$  vs Junction Temperature**



**Fig.6  $R_{ds(on)}$  vs Junction Temperature**

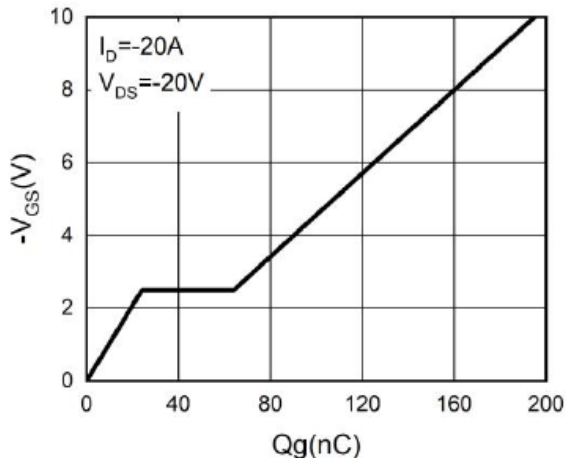


Fig.7 Gate Charge Waveforms

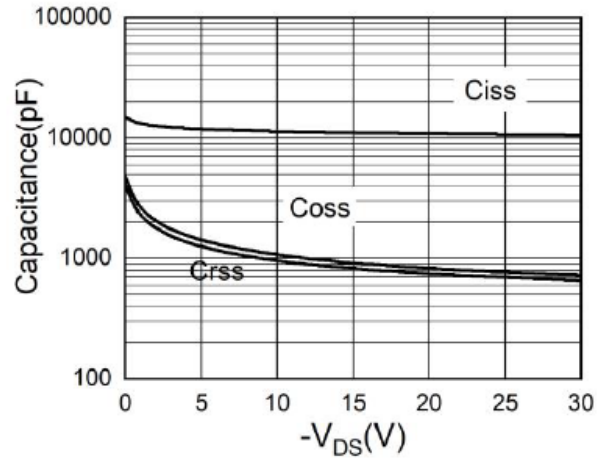


Fig.8 Capacitance

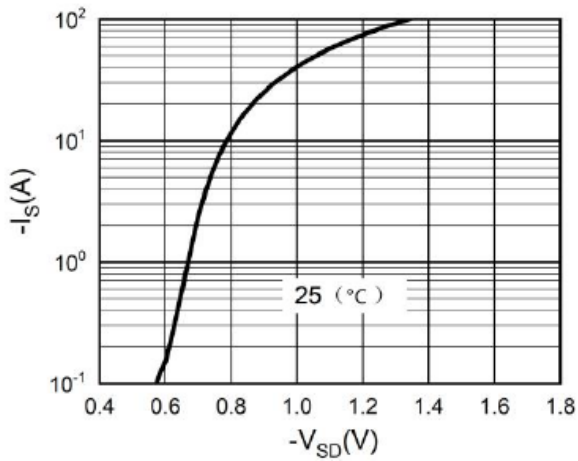


Fig.9 Body-Diode Characteristics

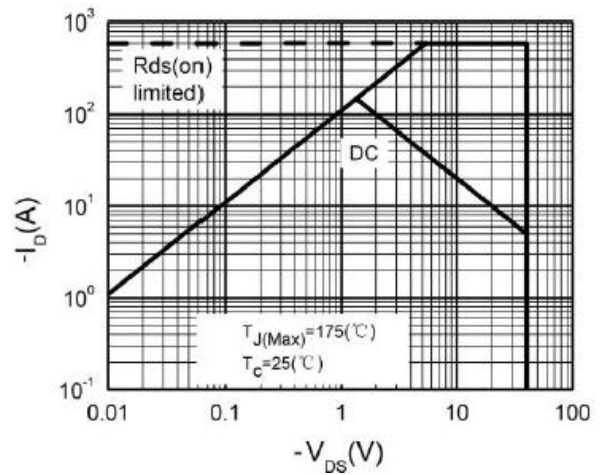
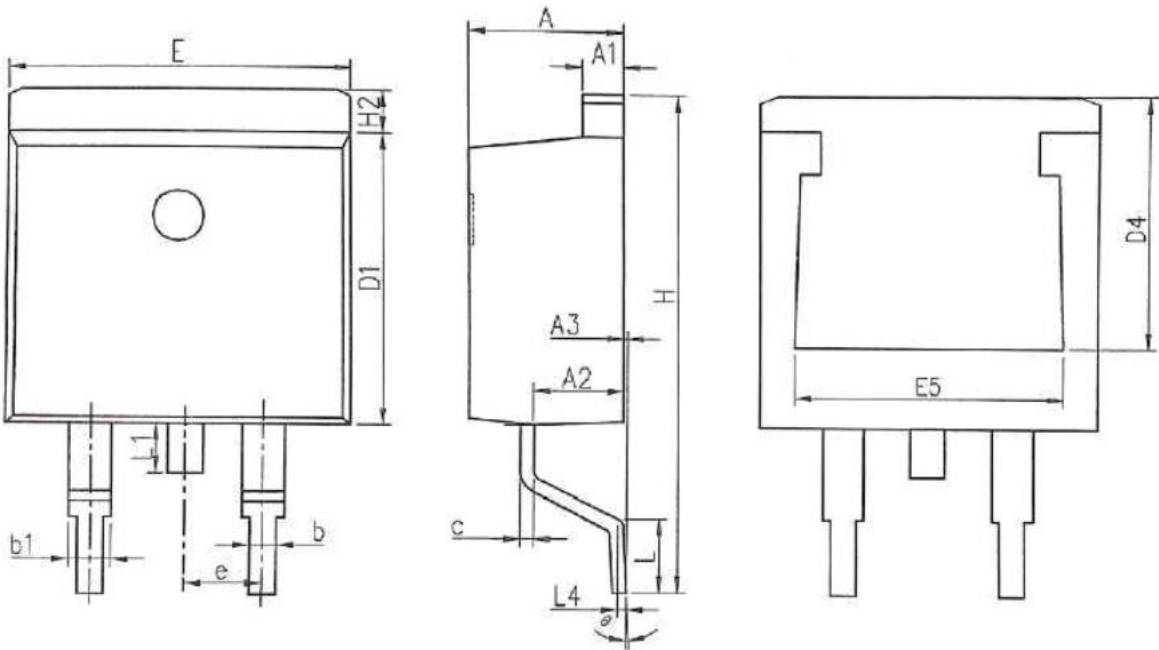


Fig.10 Maximum Safe Operating Area



| SYMBOLS | MILLIMETERS |       | INCHES    |       |
|---------|-------------|-------|-----------|-------|
|         | MIN         | MAX   | MIN       | MAX   |
| A       | 4.370       | 4.770 | 0.172     | 0.188 |
| A1      | 1.220       | 1.420 | 0.048     | 0.056 |
| A2      | 2.200       | 2.890 | 0.087     | 0.114 |
| A3      | 0.000       | 0.250 | 0.000     | 0.010 |
| b       | 0.700       | 0.960 | 0.028     | 0.038 |
| b1      | 1.170       | 1.470 | 0.046     | 0.058 |
| c       | 0.300       | 0.530 | 0.012     | 0.021 |
| D1      | 8.500       | 9.300 | 0.335     | 0.366 |
| D4      | 6.600       | -     | 0.260     | -     |
| E       | 9.860       | 10.36 | 0.388     | 0.408 |
| E5      | 7.060       | -     | 0.278     | -     |
| e       | 2.540 BSC   |       | 0.100 BSC |       |
| H       | 14.70       | 15.70 | 0.579     | 0.618 |
| H2      | 1.070       | 1.470 | 0.042     | 0.058 |
| L       | 2.000       | 2.600 | 0.079     | 0.102 |
| L1      | 1.400       | 1.750 | 0.055     | 0.069 |
| L4      | 0.250 BSC   |       | 0.010 BSC |       |
| Θ       | 0°          | 9°    | 0°        | 9°    |

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